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# 800G OSFP to 2x400G OSFP-RHS AOC Optical Transceiver Module P/N: GOO2-MDO801-XXXC

#### **Features**

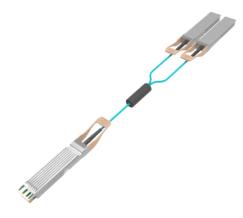
- ✓ Hot-plug OSFP and OSFP-RHS form factor
- ✓ Transmission data rate up to 106.25G per channel
- ✓ 8x106.25Gbps PAM4 transmitter and PAM4 receiver
- √ 4 channels 850nm VCSEL array and PIN photo detector array (The OSFP-RHS End)
- ✓ Power consumption <8W(The OSFP-RHS End)</p>
- √ 8 channels 850nm VCSEL array and PIN photo detector array (The OSFP End)
- ✓ Power consumption <14W(The OSFP End)</p>
- ✓ Compliant to OSFP MSA and CMIS
- ✓ Maximum link length of 30m on OM3 Multimode Fiber (MMF)and 50m on OM4 MMF with FEC
- ✓ Built-in digital diagnostic functions
- ✓ Operating case temperature 0°C to +70°C
- √ 3.3V power supply voltage
- √ RoHS compliant(lead free)

### **Applications**

- ✓ IEEE 802.3db 2 x 400GBASE-SR4 Ethernet (PAM4)
- ✓ The transceiver is designed for Ethernet, Telecom and Infiniband use cases.

#### **Description**

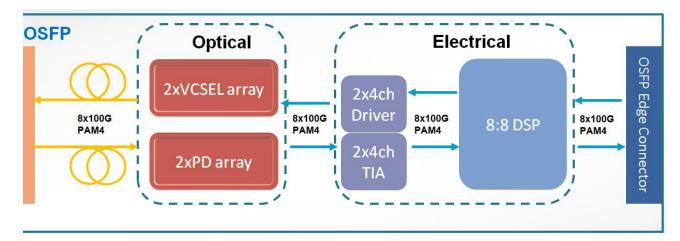
The Gigalight GOO2-MDO801-XXXC MMF Active Optical Cable is used in 8 X 100Gigabit Ethernet links over OM3/OM4 multimode fiber. The OSFP port has integrate 8 independent transmit and receive channels, each capable of 106.25Gb/s PAM4 operation for an aggregate data rate of 425Gb/s, while the OSFP-RHS port has integrate 4 independent transmit and receive channels, which provides increased port density and total system cost savings for switches and routers, etc. It is compliant with IEEE 802.3db, IEEE 802.3ck and OSFP MSA. This module incorporates Gigalight Technologies proven



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circuit and VCSEL technology to provide reliable long life, high performance, and consistent service.



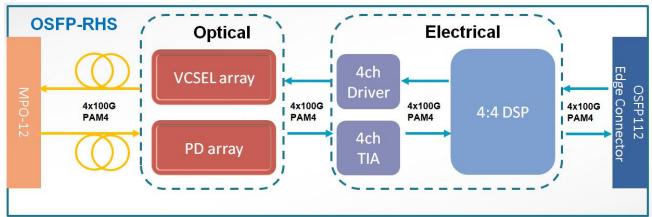


Figure 1. Module Block Diagram

## **Absolute Maximum Ratings**

Parameter	Symbol	Min	Max	Unit
Supply Voltage	Vcc	-0.3	3.6	V
Input Voltage	Vin	-0.3	Vcc+0.3	V
Storage Temperature	Tst	-20	85	$^{\circ}\!\mathbb{C}$
Case Operating Temperature	Тор	0	70	$^{\circ}$ C
Humidity(non-condensing)	Rh	5	95	%

## **Recommended Operating Conditions**

Parameter	Symbol	Min	Typical	Max	Unit
Supply Voltage	Vcc	3.13	3.3	3.47	V
Operating Case temperature T		0		70	$^{\circ}$ C
Data Rate Per Lane			106.25		Gbps



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Humidity	Rh	5		85	%
Power Dissipation(The OSFP-RHS End)	Pm		7.5	8	W
Power Dissipation(The OSFP End)	Pm		13.5	14	W

## **Electrical Specifications**

Parameter	Symbol	Min	Typical	Max	Unit
Differential input impedance	Zin	90	100	110	ohm
Differential Output impedance	Zout	90	100	110	ohm
Differential input voltage amplitude	ΔVin	400		900	mVp-p
Differential output voltage	ΔVout			850	mVp-p
Bit Error Rate	BER			2.4E-4	-
Input Logic Level High	V <sub>IH</sub>	2.0		Vcc	V
Input Logic Level Low	V <sub>IL</sub>	0		0.8	V
Output Logic Level High	V <sub>ОН</sub>	V <sub>cc</sub> -0.5		V <sub>cc</sub>	V
Output Logic Level Low	V <sub>OL</sub>	0		0.4	V
Input Logic Level High	V <sub>IH</sub>	2.0		Vcc	V

#### Note:

- 1. BER=2.4E-4; PRBS31Q@53.125GBd. Pre-FEC
- 2. Differential input voltage amplitude is measured between TxnP and TxnN.
- 3. Differential output voltage amplitude is measured between RxnP and RxnN.

## **Optical Characteristics**

**Table 3 - Optical Characteristics** 

Parameter	Symbol	Min	Typical	Max	Unit	Notes		
	Transmitter							
Centre Wavelength	λς	842	850	948	nm	-		
RMS spectral width	Δλ	-	-	0.65	nm	-		
Average launch power, each lane	Pout	-4.6	-	5.5	dBm	-		
Optical Modulation Amplitude (OMAouter), each lane	OMA	-2.6		4	dBm	-		



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Transmitter and dispersion eye closure for PAM4(TDECQ),each lane	TDECQ			4.4	dB	
Extinction Ratio	ER	2.5	-	-	dB	-
Average launch power of OFF transmitter, each lane				-30	dB	-
		Receive	r			
Centre Wavelength	λς	842	850	948	nm	-
Receiver Sensitivity in OMAout	RXsen			max (- 4.4,TECQ- 6.2)	- dBm	1
Stressed Receiver Sensitivity in OMAout	SRS			-1.8	dBm	2
Maximum Average power at receiver , each lane input, each lane				5.5	dBm	-
Minimum Average power at receiver, each lane		-6.3		dBr		1
Receiver Reflectance				-15	dB	
LOS Assert	LOSA	-15		-8.5	dBm	ı -
LOS De-Assert LOSD				-6.5	dBm	-
LOS Hysteresis	LOSH	0.5		dB		-

## Note:

- 1. Measured with conformance test signal at TP3 for BER = 2.4E-4 Pre-FEC.
- 2. These test conditions are for measuring stressed receiver sensitivity. They are not characteristics of the receiver.

# **Digital Diagnostic Specification**

Parameter	Symbol	Min	Typical	Max	Units	Notes
Transceiver Case Temperature	DMI_Temp	-3		+3	$^{\circ}$ C	Over operating temp
Supply voltage monitor absolute error	DMI_VCC	-0.1		0.1	V	Full operating range
Channel RX power monitor absolute error	DMI_RX	-2		+2	dB	Per channel
Channel Bias current monitor	DMI_Ibias	-10%		+10%	mA	Per channel

Channel TX power monitor absolute error

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+2 dB Per channel

# **Pin Description**

	III Description					
Pin	Symbol	Description	Logic	Direction		
1	GND	Ground				
2	TX2p	Transmitter Data Non- Inverted	CML-I	Input from Host		
3	TX2n	Transmitter Data Inverted	CML-I	Input from Host		
4	GND	Ground				
5	TX4p	Transmitter Data Non- Inverted	CML-I	Input from Host		
6	TX4n	Transmitter Data Inverted	CML-I	Input from Host		
7	GND	Ground				
8	TX6p	Transmitter Data Non- Inverted	CML-I	Input from Host		
9	TX6n	Transmitter Data Inverted	CML-I	Input from Host		
10	GND	Ground				
11	TX8p	Transmitter Data Non- Inverted	CML-I	Input from Host		
12	TX8n	Transmitter Data Inverted	CML-I	Input from Host		
13	GND	Ground				
14	SCL	2-wire Serial interface clock	LVCMOS-I/O	Bi- directional		
15	VCC	+3.3V Power		Power from Host		
16	VCC	+3.3V Power		Power from Host		
17	LPWn/PRSn	Low-Power Mode / Module Present	Multi-Level	Bi- directional		
18	GND	Ground				
19	RX7n	Receiver Data Inverted	CML-O	Output to Host		
20	RX7p	Receiver Data Non-Inverted	CML-O	Output to Host		
21	GND	Ground				
22	RX5n	Receiver Data Inverted	CML-O	Output to Host		
23	RX5p	Receiver Data Non-Inverted	CML-O	Output to Host		
24	GND	Ground				
25	RX3n	Receiver Data Inverted	CML-O	Output to Host		
26	RX3p	Receiver Data Non-Inverted	CML-O	Output to Host		
27	GND	Ground				
28	RX1n	Receiver Data Inverted	CML-O	Output to Host		



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29	RX1p	Receiver Data Non-Inverted	CML-O	Output to Host
30	GND	Ground		
31	GND	Ground		
32	RX2p	Receiver Data Non-Inverted	CML-O	Output to Host
33	RX2n	Receiver Data Inverted	CML-O	Output to Host
34	GND	Ground		
35	RX4p	Receiver Data Non-Inverted	CML-O	Output to Host
36	RX4n	Receiver Data Inverted	CML-O	Output to Host
37	GND	Ground		
38	RX6p	Receiver Data Non-Inverted	CML-O	Output to Host
39	RX6n	Receiver Data Inverted	CML-O	Output to Host
40	GND	Ground		
41	RX8p	Receiver Data Non-Inverted	CML-O	Output to Host
42	RX8n	Receiver Data Inverted	CML-O	Output to Host
43	GND	Ground		
44	INT/RSTn	Module Interrupt / Module Reset	Multi-Level	Bi- directional
45	VCC	+3.3V Power		Power from Host
46	VCC	+3.3V Power		Power from Host
47	SDA	2-wire Serial interface data	LVCMOS-I/O	Bi- directional
48	GND	Ground		
49	TX7n	Transmitter Data Inverted	CML-I	Input
50	TX7p	Transmitter Data Non- Inverted	CML-I	Input from Host
51	GND	Ground		
52	TX5n	Transmitter Data Inverted	CML-I	Input from Host
53	TX5p	Transmitter Data Non- Inverted	CML-I	Input from Host
54	GND	Ground		
55	TX3n	Transmitter Data Inverted	CML-I	Input from Host
56	TX3p	Transmitter Data Non- Inverted	CML-I	Input from Host
57	GND	Ground		
58	TX1n	Transmitter Data Inverted	CML-I	Input from Host
59	TX1p	Transmitter Data Non- Inverted	CML-I	Input from Host
60	GND	Ground		
		•	L	

60

59

58

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Top Side (viewed from top)

GND

TX1p

TX1n

GND

ТХ3р

TX3n

GND

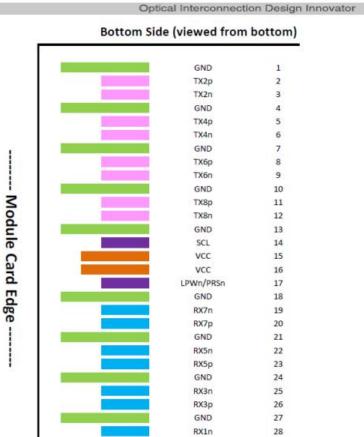
GND

RX4n

GND

RX2n

RX2p GND



RX1p

GND

29

30

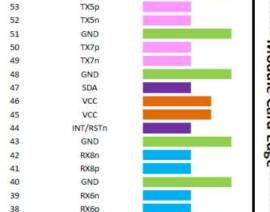


Figure 2. Electrical Pin-out Details

## **OSFP Control pins**

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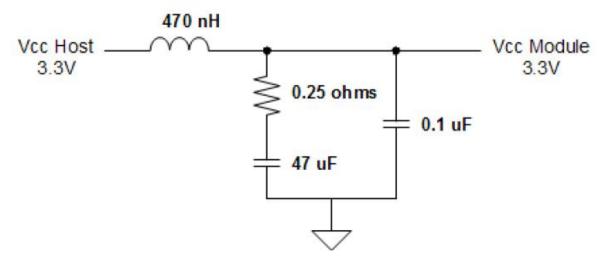
32

31

Name	Function	Description
LPWn/PRSn	Input/output	Multi-level signal for low power control from host to module and module presence indication from module to host. This signal requires the circuit as described in the OSFP Specification.
INT/RSTn	Input,/output	Multi-level signal for interrupt request from module to host and reset control from host to module. This signal requires the circuit as described in the OSFP Specification.

Name	Function	Description
SCL	BiDir	2-wire serial clock signal. Requires pull-up resistor to 3.3V on host.
SDA	Bidir	2-wire serial data signal. Requires pull-up resistor to 3.3V on host.

## **Power Supply Filtering**



The host board should use the power supply filtering shown in Figure 3.

Figure 3. Host Board Power Supply Filtering

#### DIAGNOSTIC MONITORING INTERFACE

Digital diagnostics monitoring function is available on all Gigalight OSFP products. A 2-wire serial interface provides user to contact with module.

#### **Memory Structure and Mapping**

This limits the management memory that can be directly accessed by the host to 256 bytes, which is divided in Lower Memory (addresses 00h through 7Fh) and Upper Memory (addresses 80h through FFh).

A larger addressable management memory is required for all but the most basic modules. This is supported by a structure of 128-byte pages, together with a mechanism for dynamically mapping any of the 128-byte pages from a larger internal management memory space into Upper Memory the host addressable space.

The addressing structure of the additional internal management memory is shown in Figure 4 The management memory inside the module is arranged as a unique and always host accessible address space of 128 bytes (Lower Memory) and as multiple upper address subspaces of 128 bytes each (Pages), only one of which is selected as host visible in Upper Memory. A second level of Page selection is possible for Pages for which several instances exist (e.g. where a bank of pages with the same Page number exists).

This structure supports a flat 256 byte memory for passive copper modules and permits timely access to

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addresses in the Lower Memory, e.g. Flags and Monitors. Less time critical entries, e.g. serial ID information and threshold settings, are available with the Page Select function in the Lower Page. For more complex modules which require a larger amount of management memory the host needs to use dynamic mapping of the various Pages into the host addressable Upper Memory address space, whenever needed.

**Note**: The management memory map has been designed largely after the QSFP memory map. This memory map has been changed in order to accommodate 8 electrical lanes and to limit the required memory space. The single address approach is used as found in QSFP. Paging is used in order to enable time critical interactions between host and module.

#### **Supported Pages**

A basic 256 byte subset of the Management Memory Map is mandatory for all CMIS compliant devices. Other parts are only available for paged memory modules, or when advertised by the module. See CMIS V4.0 for details regarding the advertisement of supported management memory spaces.

In particular, support of the Lower Memory and of Page 00h is required for all modules, including passive copper cables. These pages are therefore always implemented. Additional support for Pages 01h, 02h and bank 0 of Pages 10h and 11h is required for all paged memory modules.

Bank 0 of pages 10h-1Fh, provides lane-specific registers for the first 8 lanes, and each additional bank provides support for additional 8 lanes. Note, however, that the allocation of information over the banks may be page specific and may not to be related to grouping data for 8 lanes.

The structure allows address space expansion for certain types of modules by allocating additional Pages. Moreover, additional banks of pages.

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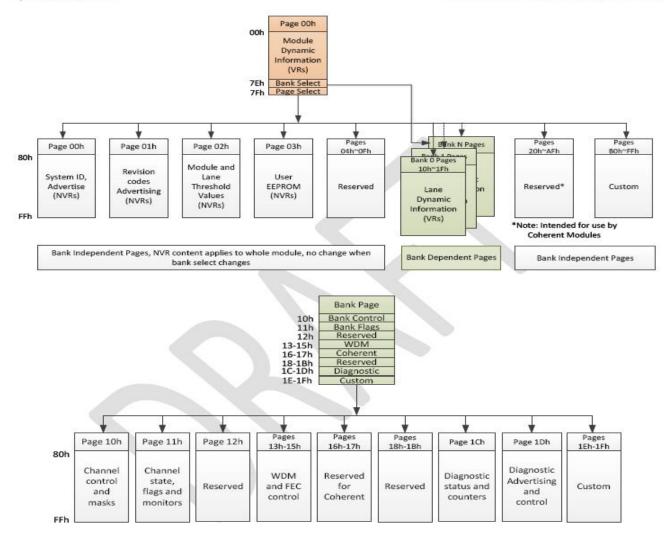


Figure 4. OSFP Memory Map

## **Mechanical Dimensions(mm)**



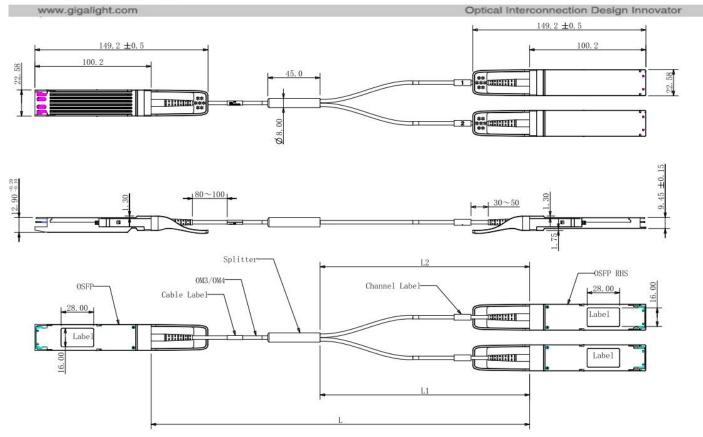


Figure 5. Mechanical Specifications

## **Regulatory Compliance**

Gigaligth GOO2-MDO801-XXXC transceivers are Class 1 Laser Products. They meet the requirements of the following standards:

Feature	Standard
Laser Safety	IEC 60825-1:2014 (3 <sup>rd</sup> Edition) IEC 60825-2:2004/AMD2:2010 EN 60825-1-2014 EN 60825-2:2004+A1+A2
Electrical Safety	EN 62368-1: 2014 IEC 62368-1:2014 UL 62368-1:2014
Environmental protection	Directive 2011/65/EU with amendment(EU)2015/863
CE EMC	EN55032: 2015 EN55035: 2017 EN61000-3-2:2014 EN61000-3-3:2013
FCC	FCC Part 15, Subpart B ANSI C63.4-2014

#### References

- 1. OSFP Module Specification Rev5 0
- 2. CMIS V4.0
- 3. IEEE 802.3db 400GBASE-VR4 Ethernet (PAM4)
- 4. IEEE802.3ck



Use of controls or adjustment or performance of procedures other than those specified herein may result in hazardous radiation exposure.

## **Ordering information**

Part Number	Product Description	
GOO2-MDO801-XXXC	800G OSFP - 2x400G OSFP-RHS AOC transceiver, 850nm, up to 50m with	
	OM4,	
	XXX: 001-1m, 005-5m, 007-7m, 020-20m, 030-30m, 050-50m	

### **Important Notice**

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#### **Revision History**

Revision	Date	Description
V0	Aug-7-2024	Advance Release.